molex



Part Number : 1720503178
Product Description : EdgeLine+ ESP Vertical Connector, 15 Gbps, 0.75mm Pitch, 1.57mm PCB Thickness, 50.0A Power Module, 178 Circuits, 2 Power Circuits
Series Number : 172050
Status : Obsolete
Product Category : Card Edge Connectors

Obsolete

Documents & Resources

Drawings

PK-172052-1000-001.pdf

SYM-172050-3178-001.zip

1720500004-000.pdf

1720500004-000.zip

Specifications

AS-172050-0001-001.pdf

PS-172050-0001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)6225-DC (07 Nov 2024)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Obsolete
Category	Card Edge Connectors
Series	172050
Description	EdgeLine+ ESP Vertical Connector, 15 Gbps, 0.75mm Pitch, 1.57mm PCB Thickness, 50.0A Power Module, 178 Circuits, 2 Power Circuits
Component Type	Edgecard to PCB
Product Name	EdgeLine
UPC	887191649726

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	3.0A
Data Rate	12.5-20.0 Gbps
High Power Bay (30.0A or more)	Yes
Voltage - Maximum	250V AC (RMS)/DC

Physical

Circuits (Loaded)	178

Obsolete

Circuits (maximum)	178
Color - Resin	Black
Durability (mating cycles max)	200
Edge Card Thickness	1.57mm
Entry Angle	N/A
Flammability	94V-0
Keying to Mating Part	N/A
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	9.323/g
Orientation	Vertical
Packaging Type	Tube
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	2.79mm
Pitch - Mating Interface	0.75mm
Pitch - Termination Interface	0.75mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
(p)ower-(s)ignal Configuration	174s - 0p
Temperature Range - Operating	-40° to +105°C
Termination Interface Style	Surface Mount

Obsolete

Solder Process Data

Max-Duration	10
Lead-Free Process Capability	REFLOW
Max-Cycle	2
Max-Temp	260